

Title (en)
TWO-STEP MOLDING FOR A LEAD FRAME

Title (de)
ZWEISTUFIGES FORMEN FÜR EINEN LEITERRAHMEN

Title (fr)
MOULAGE EN DEUX ÉTAPES POUR UNE GRILLE DE CONNEXION

Publication
EP 3687758 B1 20230712 (EN)

Application
EP 18815443 A 20181116

Priority
US 2018061597 W 20181116

Abstract (en)
[origin: WO2020101706A1] Examples for a two-step insert molding process to encapsulate a pre- molded lead frame (104, 304, 504, 704) are described herein. In some examples, a first circuit component (106, 306, 506) and a first portion of a trace array (110, 310, 510) of the pre-molded lead frame for an integrated circuit (1C) assembly are encapsulated by a first insert molding component (112, 312, 512a, 512b, 712). The trace array connects the first circuit component to a second circuit component (108, 308, 508) of the pre-molded lead frame. A second portion of the trace array is encapsulated by a second insert molding component (114, 314, 514, 714).

IPC 8 full level
B29C 45/16 (2006.01); **B29C 45/14** (2006.01); **G01D 11/24** (2006.01); **H01L 21/56** (2006.01); **H01L 23/31** (2006.01)

CPC (source: EP US)
B29C 45/1671 (2013.01 - EP); **H01L 21/568** (2013.01 - EP); **H01L 23/31** (2013.01 - US); **H01L 23/49541** (2013.01 - US); **H01L 23/49575** (2013.01 - US); **B29C 45/14655** (2013.01 - EP); **H01L 23/3107** (2013.01 - EP)

Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)
WO 2020101706 A1 20200522; CN 113039052 A 20210625; CN 113039052 B 20230905; EP 3687758 A1 20200805; EP 3687758 B1 20230712; US 11227807 B2 20220118; US 2020343153 A1 20201029

DOCDB simple family (application)
US 2018061597 W 20181116; CN 201880099494 A 20181116; EP 18815443 A 20181116; US 201816768553 A 20181116